

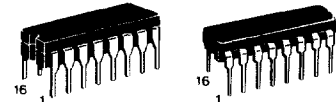
HEX TYPE D FLIP-FLOP

The MC14174B hex type D flip-flop is constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. Data on the D inputs which meets the setup time requirements is transferred to the Q outputs on the positive edge of the clock pulse. All six flip-flops share common clock and reset inputs. The reset is active low, and independent of the clock.

- Static Operation
- All Inputs and Outputs Buffered
- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low-power TTL Loads or One Low-Power Schottky TTL Load over the Rated Temperature Range
- Functional Equivalent to TTL 74174

CMOS MSI

(LOW-POWER COMPLEMENTARY MOS)

HEX TYPE D FLIP-FLOP

L SUFFIX
 CERAMIC PACKAGE
 CASE 620

P SUFFIX
 PLASTIC PACKAGE
 CASE 648

ORDERING INFORMATION
A Series: -55°C to +125°C
 MC14XXXBAL (Ceramic Package Only)

C Series: -40°C to +85°C
 MC14XXXBCP (Plastic Package)
 MC14XXXBCL (Ceramic Package)

MAXIMUM RATINGS* (Voltages Referenced to V_{SS})

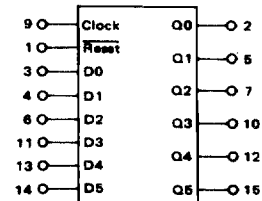
Symbol	Parameter	Value	Unit
V _{DD}	DC Supply Voltage	-0.5 to +18.0	V
V _{in} , V _{out}	Input or Output Voltage (DC or Transient)	-0.5 to V _{DD} + 0.5	V
I _{in} , I _{out}	Input or Output Current (DC or Transient), per Pin	±10	mA
P _D	Power Dissipation, per Package†	500	mW
T _{stg}	Storage Temperature	-65 to +150	°C
T _L	Lead Temperature (8-Second Soldering)	260	°C

*Maximum Ratings are those values beyond which damage to the device may occur.
 †Temperature Derating: Plastic "P" Package: -12mW/°C from 65°C to 85°C
 Ceramic "L" Package: -12mW/°C from 100°C to 125°C

TRUTH TABLE
 (Positive Logic)

Clock	INPUTS			OUTPUT	Q
	Data	Reset	Q		
	0	1	0	0	No Change
	1	1	1	1	
	X	1	Q	Q	
X	X	0	0	0	

X = Don't Care

BLOCK DIAGRAM

 V_{DD} = Pin 16
 V_{SS} = Pin 8

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range V_{SS} ≤ (V_{in} or V_{out}) ≤ V_{DD}.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

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ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V _{DD} Vdc	T _{low} *		25°C			T _{high} *		Unit
			Min	Max	Min	Typ #	Max	Min	Max	
Output Voltage V _{in} = V _{DD} or 0 V _{in} = 0 or V _{DD}	"0" Level V _{OL}	5.0	—	0.05	—	0	0.05	—	0.05	Vdc
		10	—	0.05	—	0	0.05	—	0.05	
		15	—	0.05	—	0	0.05	—	0.05	
	"1" Level V _{OH}	5.0	4.95	—	4.95	5.0	—	4.95	—	Vdc
		10	9.95	—	9.95	10	—	9.95	—	
		15	14.95	—	14.95	15	—	14.95	—	
Input Voltage (V _O = 4.5 or 0.5 Vdc) (V _O = 9.0 or 1.0 Vdc) (V _O = 13.5 or 1.5 Vdc)	"0" Level V _{IL}	5.0	—	1.5	—	2.25	1.5	—	1.5	Vdc
		10	—	3.0	—	4.50	3.0	—	3.0	
		15	—	4.0	—	6.75	4.0	—	4.0	
	"1" Level V _{IH}	5.0	3.5	—	3.5	2.75	—	3.5	—	Vdc
		10	7.0	—	7.0	5.50	—	7.0	—	
		15	11.0	—	11.0	8.25	—	11.0	—	
Output Drive Current (AL Device) (V _{OH} = 2.5 Vdc) Source (V _{OH} = 4.6 Vdc) (V _{OH} = 9.5 Vdc) (V _{OH} = 13.5 Vdc) (V _{OL} = 0.4 Vdc) Sink (V _{OL} = 0.5 Vdc) (V _{OL} = 1.5 Vdc)	I _{OH}	5.0	-3.0	—	-2.4	-4.2	—	-1.7	—	mAdc
		5.0	-0.64	—	-0.51	-0.88	—	-0.36	—	
		10	-1.6	—	-1.3	-2.25	—	-0.9	—	
		15	-4.2	—	-3.4	-8.8	—	-2.4	—	
	I _{OL}	5.0	0.64	—	0.51	0.88	—	0.36	—	mAdc
		10	1.6	—	1.3	2.25	—	0.9	—	
15		4.2	—	3.4	8.8	—	2.4	—		
Output Drive Current (CL/CP Device) (V _{OH} = 2.5 Vdc) Source (V _{OH} = 4.6 Vdc) (V _{OH} = 9.5 Vdc) (V _{OH} = 13.5 Vdc) (V _{OL} = 0.4 Vdc) Sink (V _{OL} = 0.5 Vdc) (V _{OL} = 1.5 Vdc)	I _{OH}	5.0	-2.5	—	-2.1	-4.2	—	-1.7	—	mAdc
		5.0	-0.52	—	-0.44	-0.88	—	-0.36	—	
		10	-1.3	—	-1.1	-2.25	—	-0.9	—	
		15	-3.6	—	-3.0	-8.8	—	-2.4	—	
	I _{OL}	5.0	0.52	—	0.44	0.88	—	0.36	—	mAdc
		10	1.3	—	1.1	2.25	—	0.9	—	
15		3.6	—	3.0	8.8	—	2.4	—		
Input Current (AL Device)	I _{in}	15	—	±0.1	—	±0.00001	±0.1	—	±1.0	μAdc
Input Current (CL/CP Device)	I _{in}	15	—	±0.3	—	±0.00001	±0.3	—	±1.0	μAdc
Input Capacitance (V _{in} = 0)	C _{in}	—	—	—	—	5.0	7.5	—	—	pF
Quiescent Current (AL Device) (Per Package)	I _{DD}	5.0	—	5.0	—	0.005	5.0	—	150	μAdc
		10	—	10	—	0.010	10	—	300	
		15	—	20	—	0.015	20	—	600	
Quiescent Current (CL/CP Device) (Per Package)	I _{DD}	5.0	—	20	—	0.005	20	—	150	μAdc
		10	—	40	—	0.010	40	—	300	
		15	—	80	—	0.015	80	—	600	
Total Supply Current**† (Dynamic plus Quiescent, Per Package) (C _L = 50 pF on all outputs, all buffers switching)	I _T	5.0	I _T = (1.1 μA/kHz) f + I _{DD}							μAdc
		10	I _T = (2.3 μA/kHz) f + I _{DD}							
		15	I _T = (3.7 μA/kHz) f + I _{DD}							

*T_{low} = -55°C for AL Device, -40°C for CL/CP Device.
T_{high} = +125°C for AL Device, +85°C for CL/CP Device.

**The formulas given are for the typical characteristics only at 25°C.

†To calculate total supply current at loads other than 50 pF:

#Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) V/fk$$

where: I_T is in μA (per package), C_L in pF, V = (V_{DD} - V_{SS}) in volts, f in kHz is input frequency, and k = 0.003.

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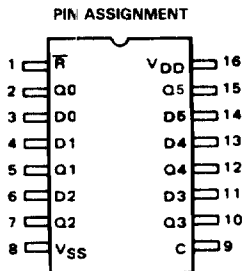
SWITCHING CHARACTERISTICS* ($C_L = 50 \text{ pF}$, $T_A = 25^\circ\text{C}$)

Characteristic	Symbol	VDD Vdc	All Types			Unit
			Min	Typ #	Max	
Output Rise and Fall Time $t_{TLH}, t_{THL} = (1.35 \text{ ns/pF}) C_L + 32 \text{ ns}$ $t_{TLH}, t_{THL} = (0.6 \text{ ns/pF}) C_L + 20 \text{ ns}$ $t_{TLH}, t_{THL} = (0.4 \text{ ns/pF}) C_L + 20 \text{ ns}$	t_{TLH}, t_{THL}	5.0 10 15	— — —	100 50 40	200 100 80	ns
Propagation Delay Time — Clock to Q $t_{PLH}, t_{PHL} = (0.9 \text{ ns/pF}) C_L + 165 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.36 \text{ ns/pF}) C_L + 64 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.26 \text{ ns/pF}) C_L + 52 \text{ ns}$	t_{PLH}, t_{PHL}	5.0 10 15	— — —	210 85 65	400 160 120	ns
Propagation Delay Time — Reset to Q $t_{PHL} = (0.9 \text{ ns/pF}) C_L + 205 \text{ ns}$ $t_{PHL} = (0.36 \text{ ns/pF}) C_L + 79 \text{ ns}$ $t_{PHL} = (0.26 \text{ ns/pF}) C_L + 62 \text{ ns}$	t_{PHL}	5.0 10 15	— — —	250 100 75	500 200 150	ns
Clock Pulse Width	t_{WH}	5.0 10 15	150 90 70	75 45 35	— — —	ns
Reset Pulse Width	t_{WL}	5.0 10 15	200 100 80	100 50 40	— — —	ns
Clock Pulse Frequency	f_{cl}	5.0 10 15	— — —	7.0 12.0 15.5	2.0 5.0 6.5	MHz
Clock Pulse Rise and Fall Time	t_{TLH}, t_{THL}	5.0 10 15	— — —	— — —	1.5 5.0 4.0	μs
Data Setup Time	t_{su}	5.0 10 15	40 20 15	20 10 0	— — 8	ns
Data Hold Time	t_h	5.0 10 15	80 40 30	40 20 15	— — —	ns
Reset Removal Time	t_{rem}	5.0 10 15	250 100 80	125 50 40	— — —	ns

*The formulas given are for the typical characteristics only at 25°C.

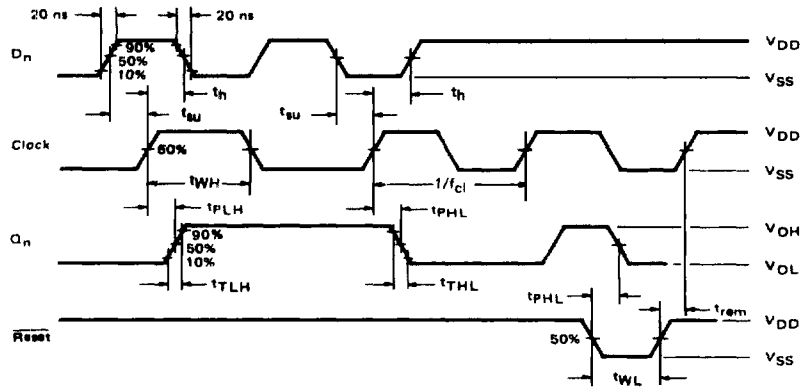
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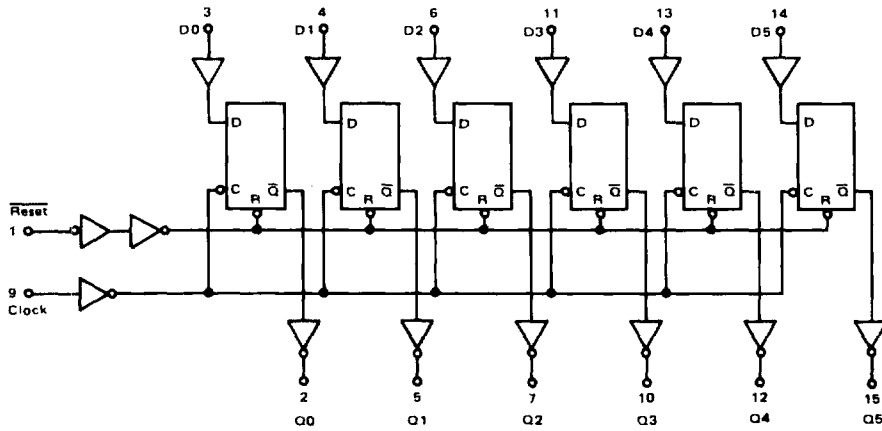


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TIMING DIAGRAM



FUNCTIONAL BLOCK DIAGRAM



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